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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-601: General test methods for materials and assemblies - Reflow soldering ability test for solder joint, and reflow heat resistance test for printed boards

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31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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EUROPEAN STANDARD

EN IEC 61189-5-601

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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 5-601: General test methods for materials and assemblies - Reflow soldering ability test for solder joint, and reflow heat resistance test for printed boards
(IEC 61189-5-601:2021)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 5-601: Méthodes d'essai générales pour les matériaux et les assemblages - Essai d'aptitude au brasage par refusion pour un joint brasé, et essai de résistance à la chaleur de refusion pour les cartes imprimées
(IEC 61189-5-601:2021)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen – Teil 5-601: Allgemeine Prüfverfahren für Materialien und Baugruppen – Prüfverfahren für die Aufschmelz-Lötfähigkeit für Lötverbindungen und die Aufschmelz-Lötwärmebeständigkeit von Leiterplatten
(IEC 61189-5-601:2021)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-5-601:2021 (E)**European foreword**

The text of document 91/1601/CDV, future edition 1 of IEC 61189-5-601, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-5-601:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-12-10
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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

<u>SIST EN IEC 61189-5-601:2021</u>		
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58
IEC 60068-2-78	NOTE	Harmonized as EN 60068-2-78
IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8
IEC 61189-5-3	NOTE	Harmonized as EN 61189-5-3
IEC 61190-1-1	NOTE	Harmonized as EN 61190-1-1
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2
IEC 61249 (series)	NOTE	Harmonized as EN 61249 (series)
IEC 61249-2-7	NOTE	Harmonized as EN 61249-2-7
IEC 61249-2-8	NOTE	Harmonized as EN 61249-2-8
IEC 61760-1:2006	NOTE	Harmonized as EN 61760-1:2006 (not modified)
IEC 62137-1-1	NOTE	Harmonized as EN 62137-1-1
IEC 62137-4:2014	NOTE	Harmonized as EN 62137-4:2014 (not modified)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2	series	Environmental testing	EN 60068-2	series
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60191-6-2	-	Mechanical standardization of semiconductor devices - Part 6-2: General rules for the preparation of outline drawings of surface mounted semiconductor devices packages - Design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball and column terminal packages	EN 60191-6-2	-
IEC 60191-6-5	-	Mechanical standardization of semiconductor devices - Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch ball grid array (FBGA)	-	-
IEC 60191-6-19	-	Mechanical standardization of semiconductor devices - Part 6-19: Measurement methods of the package warpage at elevated temperature and the maximum permissible warpage	EN 60191-6-19	-
IEC 60194-1 ¹	-	Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electronic assembly technologies	-	-

¹ Under preparation. Stage at the time of publication: IEC/FDIS 60194-1:2020.

EN IEC 61189-5-601:2021 (E)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications	EN IEC 61190-1-3	-
IEC 62137-3	-	Electronics assembly technology - Part 3: Selection guidance of environmental and endurance test methods for solder joints	EN 62137-3	-

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NORME INTERNATIONALE

**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 5-601: General test methods for materials and assemblies – Reflow soldering ability test for solder joint, and reflow heat resistance test for printed boards**

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**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –
Partie 5-601: Méthodes d'essai générales pour les matériaux et les assemblages – Essai d'aptitude au brasage par refusion pour un joint brasé, et essai de résistance à la chaleur de refusion pour les cartes imprimées**

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ELECTROTECHNICAL
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CONTENTS

FOREWORD.....	6
1 Scope.....	8
2 Normative references	8
3 Terms and definitions	9
4 Grouping of soldering processes and related test severities	10
5 Specimens.....	11
5.1 Devices.....	11
5.2 Test substrate.....	13
5.3 Solder paste	13
5.4 Solder ball	14
6 Apparatus and equipment.....	14
6.1 Constant temperature and humidity testing equipment.....	14
6.2 Device-mounting equipment.....	15
6.3 X-ray transmission equipment.....	15
6.4 Electrical resistance recorder.....	15
6.5 Warpage measurement equipment.....	15
6.6 Temperature cycling chamber	16
6.7 Pull strength test equipment.....	16
7 Tg ₁ Solder joint initial quality after reflow	16
7.1 General.....	16
7.2 Specimen preparation	16
7.3 Pre-process.....	16
7.3.1 Pre-conditioning.....	16
7.3.2 Initial measurement	16
7.3.3 Moistening process (1)	17
7.3.4 Baking and warp correction	17
7.3.5 Pre-reflow heating	17
7.3.6 Moistening process (2)	17
7.4 Assembly process.....	17
7.4.1 Solder paste printing.....	17
7.4.2 Device mounting.....	18
7.4.3 Reflow heating.....	21
7.5 Recovery	22
7.6 Final measurement	22
8 Tg ₂ warpage of component and printed boards in reflow process	22
8.1 General.....	22
8.2 Specimen preparation	22
8.3 Assembly process.....	23
8.3.1 Initial measurement	23
8.3.2 Baking and warp correction	23
8.3.3 Pre-reflow heating	23
8.4 Final measurement	23
8.4.1 Warpage measurement.....	23
8.4.2 Measurement area.....	23
8.4.3 Gap measurement	23

9	Tg ₃ Resistance to soldering heat of printed boards	25
9.1	General.....	25
9.2	Specimen preparation	26
9.3	Pre-process	26
9.3.1	Pre-conditioning	26
9.3.2	Initial measurement	26
9.3.3	Moistening process (1)	26
9.3.4	Baking and warp correction	26
9.4	Reflow heating	26
9.5	Final measurement	27
10	Tg ₄ Wetting and dewetting of a printed-board land	27
10.1	General.....	27
10.2	Specimen preparation	27
10.3	Pre-process	27
10.3.1	Pre-conditioning	27
10.3.2	Initial measurement	28
10.3.3	Moistening process (1)	28
10.3.4	Pre-baking.....	28
10.3.5	Pre-reflow heating	28
10.3.6	Moistening process (2)	28
10.4	Assembly process	28
10.4.1	Solder paste printing.....	28
10.4.2	Reflow heating.....	28
10.5	Final measurement	29
10.5.1	Measurement	29
10.5.2	Flux removal.....	30
11	Tg ₅ Resistance to dissolution of a printed-board land.....	30
11.1	General.....	30
11.2	Specimen preparation	31
11.3	Pre-process	31
11.3.1	Pre-conditioning	31
11.3.2	Initial measurement	31
11.4	Assembly process.....	31
11.4.1	Solder paste printing.....	31
11.4.2	Reflow heating.....	31
11.5	Final measurement	31
11.5.1	Observation.....	31
11.5.2	Observation method	32
11.5.3	Measurement.....	32
11.5.4	Example of influence upon occurrence of dissolution	33
12	Tg ₆ Pull strength of the test substrate land.....	33
12.1	General.....	33
12.2	Specimen preparation	34
12.3	Pre-process	34
12.3.1	Pre-conditioning	34
12.3.2	Initial measurement	34
12.3.3	Pre-baking.....	34
12.3.4	Pre-reflow heating	34

12.4	Assembly process.....	34
12.4.1	Solder paste printing.....	34
12.4.2	Solder ball placement.....	34
12.4.3	Reflow heating process.....	35
12.5	Final measurement.....	35
12.5.1	Pull strength measurement.....	35
12.5.2	Pull strength measuring method A – Probe heat bond method.....	35
12.5.3	Pull strength measuring method B – Ball pinch method.....	35
12.5.4	Pull strength measuring method C – Pin pull down method.....	36
12.5.5	Pull strength measuring method D – Lead pull method.....	36
12.5.6	Final observation.....	36
	Annex A (informative) Test process items and meaning of processing contents and condition.....	38
A.1	General.....	38
A.2	Meaning of processing contents and condition.....	38
A.3	Test process items.....	38
	Bibliography.....	40
	Figure 1 – Example of a test circuit for the electrical continuity test of a solder joint.....	12
	Figure 2 – Example of area array type packages.....	12
	Figure 3 – Example of leaded type devices.....	12
	Figure 4 – Example of leadless termination type devices.....	12
	Figure 5 – Example of connector for card type devices.....	13
	Figure 6 – Example of shielding metal components.....	13
	Figure 7 – Recommended solder ball shape.....	14
	Figure 8 – Test procedure for Tg_1	16
	Figure 9 – Example of printed conditions of solder paste.....	18
	Figure 10 – Typical reflow soldering profile for Sn63Pb37 solder alloy.....	18
	Figure 11 – Typical reflow soldering profile for Sn96,5Ag3Cu,5 solder alloy.....	19
	Figure 12 – Reflow temperature profile for soldering ability.....	20
	Figure 13 – Temperature measurement of the package device using thermocouples.....	21
	Figure 14 – Temperature measurement of other specimen using thermocouples.....	21
	Figure 15 – Test procedure for Tg_2	22
	Figure 16 – Contact point.....	24
	Figure 17 – Maximum gap.....	25
	Figure 18 – Test procedure for Tg_3	26
	Figure 19 – Test procedure for Tg_4	27
	Figure 20 – State of solder wetting.....	30
	Figure 21 – Solder contact angle.....	30
	Figure 22 – Test procedure for Tg_5	31
	Figure 23 – Evaluation of resistance to dissolution of land.....	32
	Figure 24 – Cross-section observation.....	33
	Figure 25 – Test procedure for Tg_6	34
	Figure 26 – Measuring methods for pull strength.....	35

Figure 27 – Breaking modes in pull strength test.....	37
Table 1 – Test items defined in this standard	8
Table 2 – Grouping of soldering processes and typical test severities – Overview.....	11
Table 3 – Stencil design standard for devices	15
Table 4 – Maximum reflow heating conditions	20
Table 5 – Minimum reflow heating conditions	21
Table 6 – Wetting level	29
Table A.1 – Meaning of processing contents and condition	38
Table A.2 – Test process items and clauses	39

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 5-601: General test methods for materials and assemblies –
Reflow soldering ability test for solder joint, and reflow heat
resistance test for printed boards**

FOREWORD

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IEC 61189-5-601 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1601/CDV	91/1674/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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